



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

AP/2811

In re Application of: Yamaguchi, et al.

Docket No.: TI-31471

Serial No.: 10/087,556

Examiner: Im, J.M.

Filed: 03/01/2002

Art Unit: 2811

For: Semiconductor Device and Bump Formation
Method

Conf. No.: 2191

NOV 28 2003

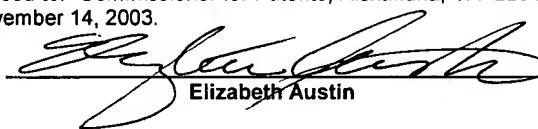
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LETTER TO THE OFFICIAL DRAFTS PERSON

Commissioner for Patents
Attn: Official Drafts Person
Alexandria, VA 22313-1450

MAILING CERTIFICATE UNDER 37 C.F.R. § 1.8(a)

I hereby certify that the above correspondence is being deposited with the U.S. Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, Alexandria, VA 22313-1450 on November 14, 2003.


Elizabeth Austin

Dear Sir:

Submitted herewith are 5 sheets of formal drawings.

The enclosed drawings are being provided in a timely manner therefore no additional fee is required.

No fee is believed by Applicant to be due; however, the Commissioner is hereby authorized and requested to charge any necessary fee to the deposit account of Texas Instruments Incorporated, Account No. 20-0668.

Respectfully submitted,



Michael K. Skrehot
Attorney for Applicants
Reg. No.: 36,682

Texas Instruments Incorporated
P. O. Box 655474, MS 3999
Dallas, Texas 75265
(972) 917-5653